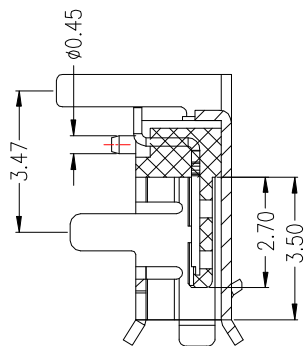
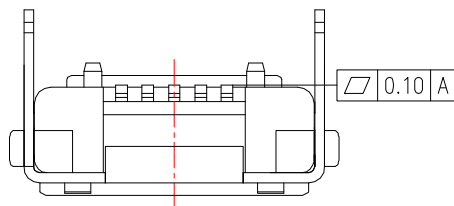
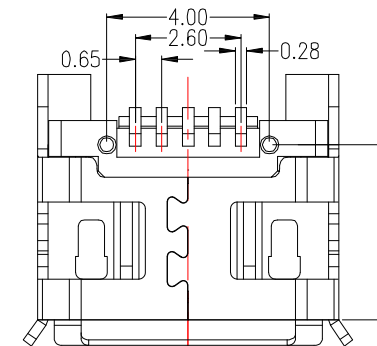
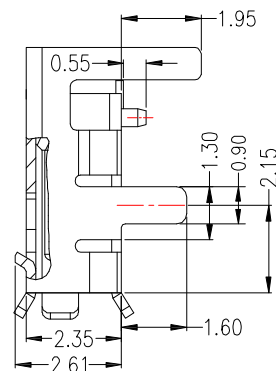
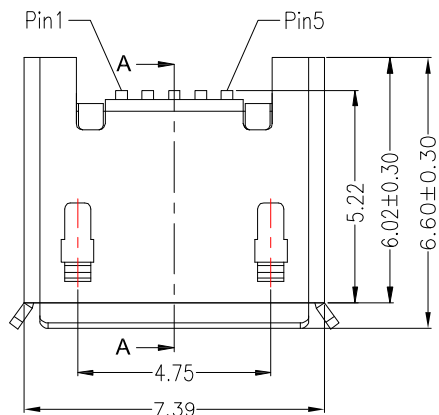




SECTION A-A



NOTES:

MATERIAL:

1.1 HOUSING: LCP

1.2 CONTACT: PHOSPHOR BRONZE

1.3 SHELL: BRASS

Finish:

2.1 Contact: Plated Gold in Mating Area :

Gold Plated on Solder Balls ;

Nickel under plated overall

2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

3.1 CURRENT RATING: 1.8 A(PIN1&5) MAX,1.0 A(PIN2&3&4) MAX

3.2 DIELECTRIC WITHSTANDING VOLTAGE: 100 V(ac) FOR 1min

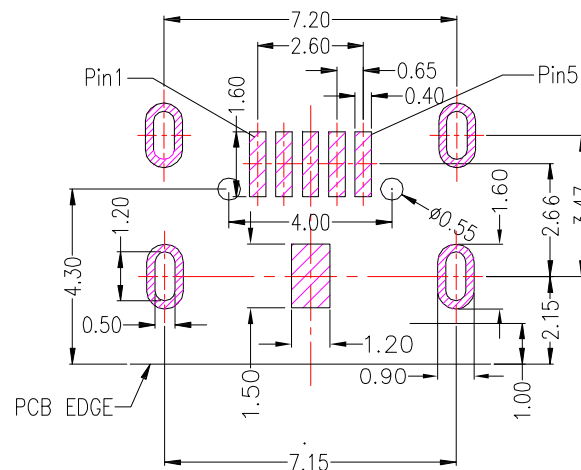
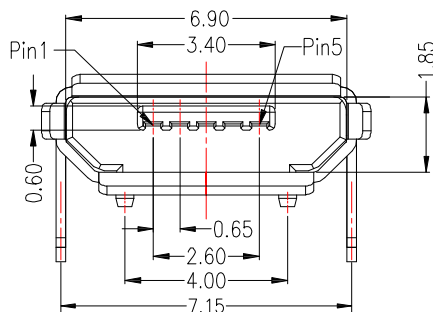
3.3 CONTACT RESISTANCE: 30 mΩ MAX.

3.4 INSULATION RESISTANCE: 100 MΩ MIN.

3.5 TOTAL MATING FORCE: 3.57 Kgf MAX.

3.6 TOTAL UNMATING FORCE: 1.0 Kgf MIN.

3.7 TEMPERATURE RANGE: -30°C ~ +80°C



P.C.B LAYOUT MOUNTING PATTERN

8	新增PCB LAYOUT尺寸和更新底部樣式	Jack	081624
7	新增尺寸	Jack	121319
6	新增尺寸	Jack	121219
5	更新樣式	Lan	050619
4	更新底部樣式	Jack	030419
ITEM NO.	DESCRIPTION	DRAWN	DATE

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED:	Up to 5	±0.2	3RD. ANGEL'S		UNITS	MM
	Above 5 ~ 15	±0.3				
	Above 15 ~ 30	±0.4				
	Above 30 ~ 50	±0.5				
	Angle	±0.3°				

DRAWN BY:	DATE
-----------	------

Jack Lu	08/16/24
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CHECKED BY:	DATE
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Jacky Chen 08/16/24

APPROVED BY:	DATE:
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3.5.1. **FIELD**

FINISH

SCALE

	CRITERIA
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MODI

DWG 1

	CONFIDENTIAL
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MICRO USB B TYPE SHELL DIPx4: 7.15 ;
W/embossing

D. MRUSB-5B-ED7NI-S347

	SIZE
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A4

VER
